

Global 3D Semiconductor Packaging Market Analysis and Forecast, 2022-2028

Market Report | 2023-02-23 | 110 pages | RationalStat

AVAILABLE LICENSES:

- Single User License \$4220.00
- Multi User License \$5870.00
- Corporate License \$7520.00

Report description:

Global 3D Semiconductor Packaging Market Analysis and Forecast, 2022-2028

The global 3D semiconductor packaging market is expected to grow at a CAGR of 13.7% over the forecast period of 2022-2028.

Market Scope & Overview

The global 3D semiconductor packaging market study by RationalStat comprises comprehensive market analysis and insights across the key market segments and geography. The market report analyzes the global market for the historical period of 2019-2021 and the forecast period of 2022-2028 based on the product installed base, key forecasting factors impacting the market conditions, and major market developments happening in the market throughout the analysis period. RationalStat practices primary and secondary research for conducting an insightful market study. Various market parameters such as macroeconomic conditions, market environment, government policies, and competitive landscape are thoroughly studied and taken into account while analyzing the market.

The global 3D semiconductor packaging market report also covers value chain and supply chain analysis that provides in-depth information about the value addition at each stage of the product. Market dynamics incorporated in the market study include drivers, restraints/challenges, trends, and their impact on the market throughout the analysis period. The market study also covers the pricing analysis of each product based on its types and regions.

The global 3D semiconductor packaging market includes a market share analysis and market structure overview with detailed company profiling of leading players with their financials, product offerings, major developments, etc. This enables clients and report buyers to make strong, precise, and timely decisions.

State of Global Economy, COVID-19 Outbreak, and the Russo-Ukraine War Impact

The global economy experienced heavy headwinds, throughout 2019-2021, as some countries witnessed subdued growth, while other countries continued to grapple with economic slowdowns. Also, intensifying tension between the US and Iran along with the tightening sanctions on Venezuela by the US further hampered global economic growth in 2019. Moreover, the heightened trade war between the US and China and the rising trade uncertainty continued to exert adverse effects on the global economy. Amid all these, the COVID-19 outbreak at the end of the year 2019 in Wuhan, China further deteriorated global economic growth.

The COVID-19 pandemic has levied undue pressure across the majority of industries globally and has caused a major economic crisis in the US, India, Italy, UK, Germany, India, Japan, South Korea, the UK, and many others. Many of these countries had

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

announced partial or complete nationwide lockdowns. The governments of several nations have called on people to shelter in place at home, travel restrictions, shut down local businesses, and prohibited social gatherings.

The rapid spread of the virus in the early month of 2020 followed by a second wave of COVID-19 caused a significant change in management strategies of the leading industries which have affected the market or industry at a significant level. Besides, the exit of the UK from the European Union earlier in 2020 and the Russo-Ukraine war in 2022 exacerbated the ever-heightened global uncertainty.

Key Market Segmentation and Companies

RationalStat has segmented the global 3D semiconductor packaging market based on material, technology, industry vertical, and region.

- By Material

- o Organic Substrate

- o Bonding Wire

- o Leadframe

- o Encapsulation

- o Resins

- o Ceramic Packages

- o Die Attach Material

- By Technology

- o 3D Wire Bonded

- o 3D Through Silicon Via

- o 3D Package on Package

- o 3D Fan Out Based

- By Industry Vertical

- o Electronics

- o Industrial

- o Automotive & Transport

- o Healthcare

- o IT & Telecommunication

- o Aerospace & Defense

- By Region

- o North America

- US

- Canada

- o Latin America

- Brazil

- Mexico

- Rest of Latin America

- o Western Europe

- Germany

- UK

- France

- Spain

- Italy

- Benelux

- Nordic

- Rest of Western Europe

- o Eastern Europe

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

- Russia
- Poland
- Rest of Eastern Europe
- o□Asia Pacific
- China
- Japan
- India
- South Korea
- Australia
- ASEAN (Indonesia, Vietnam, Malaysia, etc.)
- Rest of Asia Pacific
- o□Middle East & Africa
- GCC
- South Africa
- Turkey
- Rest of the Middle East & Africa

- Leading Companies and Market Players
- o□Amkor Technology, Inc.
- o□Jiangsu Changjiang Electronics Technology Co., Ltd.
- o□International Business Machines Corporation (IBM)
- o□Qualcomm Technologies, Inc.
- o□Intel Corporation
- o□Taiwan Semiconductor Manufacturing Company Ltd.
- o□STMicroelectronics N.V.
- o□Siliconware Precision Industries Co., Ltd. (Spil)
- o□Suss Microtec Ag.
- o□Ase Group

Table of Contents:

Global 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028

Table of Contents

- 1.□Market Introduction
 - 1.1.□Scope of Study
 - 1.2.□Problem Statement
 - 1.3.□Market Segmentation
- 2.□Assumptions and Acronyms
- 3.□Executive Summary
 - 3.1.□Global Market in 2022
 - 3.2.□Analyst Insights & Recommendations□
 - 3.3.□Growth Opportunities and Key Strategies
 - 3.4.□Supply-side and Demand-side Trends
- 4.□Research Methodology
- 5.□Analysis of COVID-19 Impact and Road Ahead
- 6.□Market Indicators and Background

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

- 6.1.□Macro-Economic Factors
- 6.2.□Forecasting Factors
- 6.3.□Supply Chain & Value Chain Analysis
- 6.4.□Industry SWOT Analysis
- 6.5.□PESTLE Analysis
- 6.6.□Porter's Five Forces Analysis
- 7.□Government Laws and Industry Regulations
- 8.□Global and Regional Market Dynamics
 - 8.1.□Drivers
 - 8.2.□Restraints
 - 8.3.□Trends
 - 8.4.□Opportunities□□□□□□
- 9.□Pricing Analysis
 - 9.1.□By Material
 - 9.1.1.□Organic Substrate
 - 9.1.2.□Bonding Wire
 - 9.1.3.□Leadframe
 - 9.1.4.□Encapsulation
 - 9.1.5.□Resins
 - 9.1.6.□Ceramic Packages
 - 9.1.7.□Die Attach Material
- 10.□Technology Analysis
- 11.□Parent Market Overview
 - 11.1.□Global Packaging Market
 - 11.2.□Global Semiconductor Market
- 12.□Segmental Analysis
 - 12.1.□Global 3D Semiconductor Packaging Market by Material
 - 12.1.1.□Segment Overview
 - 12.1.1.1.□Organic Substrate
 - 12.1.1.2.□Bonding Wire
 - 12.1.1.3.□Leadframe
 - 12.1.1.4.□Encapsulation
 - 12.1.1.5.□Resins
 - 12.1.1.6.□Ceramic Packages
 - 12.1.1.7.□Die Attach Material
 - 12.2.□Global 3D Semiconductor Packaging Market by Technology
 - 12.2.1.□Segment Overview
 - 12.2.1.1.□3D Wire Bonded
 - 12.2.1.2.□3D Through Silicon Via
 - 12.2.1.3.□3D Package on Package
 - 12.2.1.4.□3D Fan Out Based
 - 12.3.□Global 3D Semiconductor Packaging Market by Industry Vertical
 - 12.3.1.□Segment Overview
 - 12.3.1.1.□Electronics
 - 12.3.1.2.□Industrial
 - 12.3.1.3.□Automotive & Transport
 - 12.3.1.4.□Healthcare

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

- 12.3.1.5. IT & Telecommunication
- 12.3.1.6. Aerospace & Defense
- 12.4. Global 3D Semiconductor Packaging Market by Region
 - 12.4.1. North America
 - 12.4.2. Latin America
 - 12.4.3. Western Europe
 - 12.4.4. Eastern Europe
 - 12.4.5. Asia Pacific
 - 12.4.6. Middle East & Africa
- 13. Regional Analysis
 - 13.1. North America 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028
 - 13.1.1. Regional Market Overview and Key Takeaways
 - 13.1.2. North America 3D Semiconductor Packaging Market by Material
 - 13.1.3. North America 3D Semiconductor Packaging Market by Technology
 - 13.1.4. North America 3D Semiconductor Packaging Market by Industry Vertical
 - 13.1.5. North America 3D Semiconductor Packaging Market by Country
 - 13.1.5.1. US
 - 13.1.5.2. Canada
 - 13.2. Latin America 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028
 - 13.2.1. Regional Market Overview and Key Takeaways
 - 13.2.2. Latin America 3D Semiconductor Packaging Market by Material
 - 13.2.3. Latin America 3D Semiconductor Packaging Market by Technology
 - 13.2.4. Latin America 3D Semiconductor Packaging Market by Industry Vertical
 - 13.2.5. Latin America 3D Semiconductor Packaging Market by Country
 - 13.2.5.1. Brazil
 - 13.2.5.2. Mexico
 - 13.2.5.3. Rest of Latin America
 - 13.3. Western Europe 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028
 - 13.3.1. Regional Market Overview and Key Takeaways
 - 13.3.2. Western Europe 3D Semiconductor Packaging Market by Material
 - 13.3.3. Western Europe 3D Semiconductor Packaging Market by Technology
 - 13.3.4. Western Europe 3D Semiconductor Packaging Market by Industry Vertical
 - 13.3.5. Western Europe 3D Semiconductor Packaging Market by Country
 - 13.3.5.1. Germany
 - 13.3.5.2. UK
 - 13.3.5.3. France
 - 13.3.5.4. Spain
 - 13.3.5.5. Italy
 - 13.3.5.6. Benelux
 - 13.3.5.7. Nordic
 - 13.3.5.8. Rest of Western Europe
 - 13.4. Eastern Europe 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028
 - 13.4.1. Regional Market Overview and Key Takeaways
 - 13.4.2. Eastern Europe 3D Semiconductor Packaging Market by Material
 - 13.4.3. Eastern Europe 3D Semiconductor Packaging Market by Technology
 - 13.4.4. Eastern Europe 3D Semiconductor Packaging Market by Industry Vertical
 - 13.4.5. Eastern Europe 3D Semiconductor Packaging Market by Country

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

- 13.4.5.1. Russia
- 13.4.5.2. Poland
- 13.4.5.3. Rest of Eastern Europe
- 13.5. Asia Pacific 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028
- 13.5.1. Regional Market Overview and Key Takeaways
- 13.5.2. Asia Pacific 3D Semiconductor Packaging Market by Material
- 13.5.3. Asia Pacific 3D Semiconductor Packaging Market by Technology
- 13.5.4. Asia Pacific 3D Semiconductor Packaging Market by Industry Vertical
- 13.5.5. Asia Pacific 3D Semiconductor Packaging Market by Country
- 13.5.5.1. China
- 13.5.5.2. Japan
- 13.5.5.3. India
- 13.5.5.4. South Korea
- 13.5.5.5. Australia
- 13.5.5.6. ASEAN
- 13.5.5.7. Rest of Asia-Pacific
- 13.6. Middle East & Africa 3D Semiconductor Packaging Market Analysis and Forecast 2019-2028
- 13.6.1. Regional Market Overview and Key Takeaways
- 13.6.2. Middle East & Africa 3D Semiconductor Packaging Market by Material
- 13.6.3. Middle East & Africa 3D Semiconductor Packaging Market by Technology
- 13.6.4. Middle East & Africa 3D Semiconductor Packaging Market by Industry Vertical
- 13.6.5. Middle East & Africa 3D Semiconductor Packaging Market by Country
- 13.6.5.1. GCC
- 13.6.5.2. South Africa
- 13.6.5.3. Turkey
- 13.6.5.4. Rest of the Middle East & Africa
- 14. Competitive Landscape
- 14.1. Competition Dashboard
- 14.1.1. Global and Regional Market Share Analysis
- 14.1.2. Market Structure
- 14.2. Competitive Benchmarking
- 14.3. Key Strategy Analysis
- 14.4. Company Profiles
- 14.4.1. Amkor Technology, Inc.
- 14.4.1.1. Company Overview
- 14.4.1.2. Product/Service Offerings
- 14.4.1.3. Financials
- 14.4.1.4. Recent Developments
- 14.4.2. Jiangsu Changjiang Electronics Technology Co., Ltd.
- 14.4.2.1. Company Overview
- 14.4.2.2. Product/Service Offerings
- 14.4.2.3. Financials
- 14.4.2.4. Recent Developments
- 14.4.3. International Business Machines Corporation (IBM)
- 14.4.3.1. Company Overview
- 14.4.3.2. Product/Service Offerings
- 14.4.3.3. Key Financials

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

- 14.4.3.4. Recent Developments
- 14.4.4. Qualcomm Technologies, Inc.
 - 14.4.4.1. Company Overview
 - 14.4.4.2. Product/Service Offerings
 - 14.4.4.3. Key Financials
 - 14.4.4.4. Recent Developments
- 14.4.5. Intel Corporation
 - 14.4.5.1. Company Overview
 - 14.4.5.2. Product/Service Offerings
 - 14.4.5.3. Financials
 - 14.4.5.4. Recent Developments
- 14.4.6. Taiwan Semiconductor Manufacturing Company Ltd.
 - 14.4.6.1. Company Overview
 - 14.4.6.2. Product/Service Offerings
 - 14.4.6.3. Financials
 - 14.4.6.4. Recent Developments
- 14.4.7. STMicroelectronics N.V.
 - 14.4.7.1. Company Overview
 - 14.4.7.2. Product/Service Offerings
 - 14.4.7.3. Financials
 - 14.4.7.4. Recent Developments
- 14.4.8. Siliconware Precision Industries Co., Ltd. (SPIL)
 - 14.4.8.1. Company Overview
 - 14.4.8.2. Product/Service Offerings
 - 14.4.8.3. Financials
 - 14.4.8.4. Recent Developments
- 14.4.9. Suss Microtec AG
 - 14.4.9.1. Company Overview
 - 14.4.9.2. Product/Service Offerings
 - 14.4.9.3. Financials
 - 14.4.9.4. Recent Developments
- 14.4.10. ASE Group
 - 14.4.10.1. Company Overview
 - 14.4.10.2. Product/Service Offerings
 - 14.4.10.3. Financials
 - 14.4.10.4. Recent Developments

A comprehensive list of 3D semiconductor packaging brands/manufacturers by country will be provided along with geographical reach, employee count, revenue, product capacities, and their capabilities.

15. Disclaimer

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com

Global 3D Semiconductor Packaging Market Analysis and Forecast, 2022-2028

Market Report | 2023-02-23 | 110 pages | RationalStat

To place an Order with Scotts International:

- ☐ - Print this form
- ☐ - Complete the relevant blank fields and sign
- ☐ - Send as a scanned email to support@scotts-international.com

ORDER FORM:

Select license	License	Price
	Single User License	\$4220.00
	Multi User License	\$5870.00
	Corporate License	\$7520.00
		VAT
		Total

*Please circle the relevant license option. For any questions please contact support@scotts-international.com or 0048 603 394 346.

☐ ** VAT will be added at 23% for Polish based companies, individuals and EU based companies who are unable to provide a valid EU Vat Numbers.

Email*	<input type="text"/>	Phone*	<input type="text"/>
First Name*	<input type="text"/>	Last Name*	<input type="text"/>
Job title*	<input type="text"/>		
Company Name*	<input type="text"/>	EU Vat / Tax ID / NIP number*	<input type="text"/>
Address*	<input type="text"/>	City*	<input type="text"/>
Zip Code*	<input type="text"/>	Country*	<input type="text"/>
		Date	<input type="text" value="2025-05-05"/>
		Signature	<input type="text"/>

Scotts International. EU Vat number: PL 6772247784

tel. 0048 603 394 346 e-mail: support@scotts-international.com

www.scotts-international.com